



2009 SW Test Workshop Preliminary Agenda and Technical Program

The Technical Program and Conference Agenda are subject to change without notice.

	SUNDAY (June 7, 2009)	MONDAY (June 8, 2009)	TUESDAY (June 9, 2009)	WEDNESDAY (June 10, 2009)
7:00 AM		REGISTRATION AND CONTINENTAL BREAKFAST (700 to 800AM)	CONTINENTAL BREAKFAST (700 to 800AM)	CONTINENTAL BREAKFAST (700 to 800AM)
7:30 AM		WELCOME (800 to 830AM) Welcome to SWTW-2009 Jerry Broz, Ph.D., General Chair	Controlling Cres (800 to 1000AM) Clean the Wafer, Not the Probe Card Terence Q. Collier (CVIInc)	Standards and Methods (800 to 1000AM) Effective Integration of Advanced Probe Card Technologies from Development to Production Test Floors Norman Armendariz, Ph.D., James Tong (Texas Instruments) Fred Megna, Sato Minoru (MJC)
8:00 AM		Large Array Probing (830 TO 1000AM) Highest Parallel Test for DRAM Enabled through Advanced TRE (Tester Resource Enhancement) Michael Huebner, Ph.D. (Formfactor)	Investigating Copper Metallurgy Effects for Sort Process and Cleaning Performance Metrics Jan Martens (NXP Semiconductors), Simon Algaier (Feinmetall GmbH) Jerry Broz, Ph.D. (International Test Solutions)	50-um Pitch Vertical Probing John Wolfe, Norman Armendariz, Ph.D., James Tong (Texas Instruments) Fred Megna, Sato Minoru (MJC)
8:30 AM		Force Controlled Probing using Bucking Beam Contact Technology Scott Lindsey, Ph.D., Chris Buchholz (Aehr Test Systems) Simon Algaier, Gunther Boehm (Feinmetall GmbH)	Advances in Offline Reshaping and Cleaning for Cantilever, Vertical and Lithographic Probe Cards – Tip Diameter Control for POAA Rainer Gaggi, Ph.D. (TIPS), Dominique Langlois (Alis Semiconductor)	ISMI Probe Council - Current Carrying Capability Measurement Standard Boyd Daniels (Texas Instruments), Tom Wear (ISMI)
9:00 AM		A Challenge of 150k Probes on 300mm Satoshi Sasaki, Yoshiro Nakata (Association of Super-Advanced Electronics Technologies, ASET)	A Non Destructive Cleaning Solution for Probe Card Optimizing Test Floor Yield and Cost of Ownership Herve Alle (SEMI Consulting)	TBD Frank J. Swiatowiec, Sammy Mok (VeraConnex, LLC)
9:30 AM		BREAK (1000 to 1030AM)	BREAK (1000 to 1030AM)	BREAK (1000 to 1030AM)
10:00 AM		Signal Integrity (1030AM to Noon) Issues in Power Delivery System Performance Verification Gert Hohenwarter (GateWave Northern)	RF Probing (1030AM to Noon) Overcoming Challenges of High Multi-site, High Multi-port RF Wafer Sort Testing Daniel Watson (Teradyne)	Probe Potpourri (1030AM to 1200) Brittle Fracture of Ceramics - Introduction to Mechanical Behavior of Ceramics Krzysztof Dabrowiecki (Probelogic)
10:30 AM		Kelvin Contactors for Wafer Scale Test Jim Brandes (Everett Charles Technologies)	mmWave RFIC Probing Systems for Engineering and Production Test Roger Hayward (Cascade Microtech), Mark Roos (Roos Instruments)	Massively Parallel, Discrete Node Low Force Space Transformers Gordon A. Vinther (Ardent Concepts)
11:00 AM		Optimization of Wafer Level Test Hardware using Signal Integrity Simulation Jason Mroczkowski, Ryan Satrom (Everett Charles Technologies)	Improving Infinion's Probing Yield with Microprobe Vx-RF Probe Card January Kister, Mike Slesator, Ph.D., (Microprobe) Christian Degan, Ph.D., Oliver Nagler, Ph.D., (Infinion)	TBD
11:30 AM		LUNCH (Noon to 100PM)	LUNCH (Noon to 100PM)	AWARDS CEREMONY (Noon to 1230)
12:00 PM			Paradise Lawn (BBQ)	
12:30 PM		Sort Floor Data (100 to 300PM) A Probe Data Collection System - Test Head Curmap (THC) Mark Winn (Intel)	Damage Control and Low Force Probing (100PM to 300PM) High Speed Pre-Probe Wafer Inspection for Whole Wafer Probing Bojko Vodanovic, Brad Lawrence (Acetris-3D Instruments)	
1:00 PM		Test Data Validation Rob Marcellis (Salland Engineering)	Evaluation of Low Pressure MEMS Probes Scott Clegg, Krzysztof Dabrowiecki (Probelogic) Shoichi Asanuma (TOTO), Darren James (Rudolph Technologies)	
1:30 PM		High Speed 3D Probe Mark Inspection Kevin Watson (Texas Instruments), Brad Lawrence (Acetris-3D Instruments), Sung Park (Park Systems)	MEMS Technology - Enabling Design Flexibility for Fine Pitch Probing Bahadır Tunaboylu, Ph.D., Gerald Back (SV Probe)	
2:00 PM		Cost Effective Probe Card Metrology Tools Rod Shwartz (Integrated Technology Corp)	An Experimental Work and Analysis of Vertical Cobra Probing on Low-k Wafers Gary Liu, Thompson Hsu, Yuan Huang (UMC), Wensen Hung, Cahns Lin, Dean Yang (MPI)	
2:30 PM		BREAK (300 to 330PM)	BREAK (300 to 330PM)	
3:00 PM	Tutorial: (300 to 500PM) Applied Metrology and Tool Gauge Studies Darren James (Rudolph)	High Temperature (330 to 5000PM) Hot Spot: High Temperature Probing Gunther Boehm (Feinmetall GmbH)	EXHIBITS OPEN Sodas and Cookies will be served (300PM to 500PM)	
3:30 PM		Improving Scrub Performance and Reducing Soak Time with a New Mechanism to Stabilize Probe Card Temperature Cameron Harker, Jeff Lin, Stuart Pearce (Formfactor)		
4:00 PM		Novel Optical SerDes Memory Test System for High-Speed and Multi-Parallel Test Sang-Hoon Lee, Ph.D. (Samsung Electronics)		
4:30 PM				
4:30 PM				
5:00 PM				
5:30 PM	REGISTRATION and RECEPTION (500 to 700 PM)	TBD		
6:00 PM				
6:30 PM				
7:00 PM				
7:30 PM	BUFFET DINNER (700 to 815 PM)	EXHIBITS OPEN CARVING STATION DINNER (600 to 900PM)	Casino Night at the Resort! (600 TO 1000PM) Reception, Dinner, Casino Royal	
8:00 PM	PROBE YEAR IN REVIEW (815 to 900 PM) Jerry Broz, Ph.D., General Chair			
8:30 PM				
9:00 PM	KEYNOTE (900 to 945 PM) Risto Puhakka President VLSI Research Semiconductor Market Outlook	BAREFOOT BAR for NETWORKING		
9:30 PM	BAREFOOT BAR for NETWORKING			